



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 151 FR4 55 L93.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly
Layer-1	55 μ	Copper		 
	100 μ	Prepreg	(100 μ PrePreg-Type: 2125)	
	100 μ	Prepreg		
Layer-2	35 μ	Copper		
	930 μ	L-FR4		
Layer-3	35 μ	Copper		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-99	55 μ	Copper	